

# GSM03N20

## 200V N-Channel MOSFETs

### Product Description

These N-Channel enhancement mode power field effect transistors are planar stripe, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

These devices are well suited for high efficiency switch mode power supply

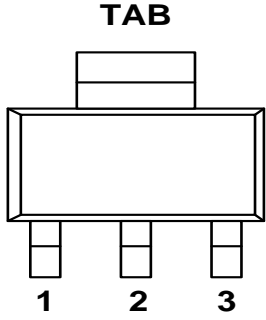
### Features

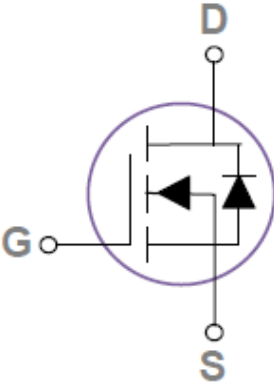
- 200V, 3A,  $R_{DS(ON)}=850m\Omega@V_{GS}=15V$
- Improved  $dv/dt$  capability
- Fast switching
- Green Device Available

### Applications

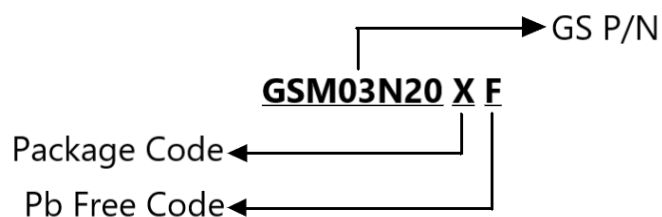
- Networking
- TV Power
- Adapter/charger
- Server Power
- High efficient switched mode power supplies

### Packages & Pin Assignments

GSM03N20XF (SOT-223)	
 <p>Top View</p>	
<b>Pin</b>	<b>Description</b>
1	Gate
2	Source
3	Drain

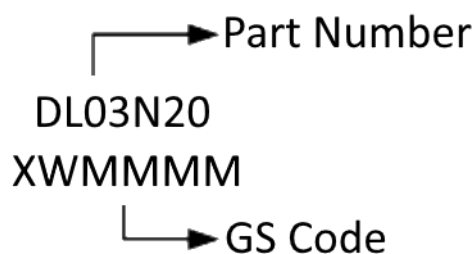


## Ordering Information



Part Number	Package	Quantity Reel
GSM03N20XF	SOT-223	2500 PCS

## Marking Information



## Absolute Maximum Ratings

$T_C=25^\circ\text{C}$  Unless otherwise noted

Symbol	Parameter	Typical	Unit
$V_{DS}$	Drain-Source Voltage	200	V
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$I_D$	Continuous Drain Current	$T_C=25^\circ\text{C}$	3
		$T_C=100^\circ\text{C}$	1.9
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	12	A
$P_D$	Power Dissipation ( $T_C=25^\circ\text{C}$ )	1.78	W
	Power Dissipation (Derate above $25^\circ\text{C}$ )	0.014	W/ $^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to +150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	70	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case	20	$^\circ\text{C}/\text{W}$

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.

## Electrical Characteristics

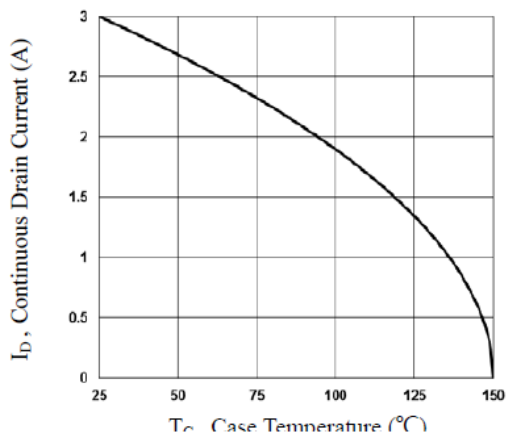
T<sub>J</sub>=25°C Unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	200	---	---	V
$\frac{\Delta V_{(BR)DSS}}{\Delta T_J}$	V <sub>(BR)DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.5	---	V/°C
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	3	4	5	V
$\Delta V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient		---	-8	---	mV/°C
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±30V	---	---	±100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =200V, V <sub>GS</sub> =0V T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =160V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	10	
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	3	A
I <sub>SM</sub>	Pulsed Source Current		---	---	6	
R <sub>DS(on)</sub>	Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =2A	---	0.7	0.85	Ω
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =2A	---	3.6	--	S
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V
<b>Dynamic</b>						
Q <sub>g</sub>	Total Gate Charge <sup>2,3</sup>	V <sub>DS</sub> =160V, V <sub>GS</sub> =10V, I <sub>D</sub> =1A	---	4.8	9	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2,3</sup>		---	2	4	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2,3</sup>		---	0.8	2	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz	---	266	500	pF
C <sub>oss</sub>	Output Capacitance		---	160	300	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	55	110	
t <sub>d(on)</sub>	Turn-On Time <sup>2,3</sup>	V <sub>DD</sub> =100V, V <sub>GS</sub> =10V, R <sub>G</sub> =25Ω, I <sub>D</sub> =1A	---	10	20	ns
t <sub>r</sub>			---	35	70	
t <sub>d(off)</sub>	Turn-Off Time <sup>2,3</sup>		---	10	20	
t <sub>f</sub>			---	28	56	
R <sub>g</sub>	Gate resistance		V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHZ		1.5	

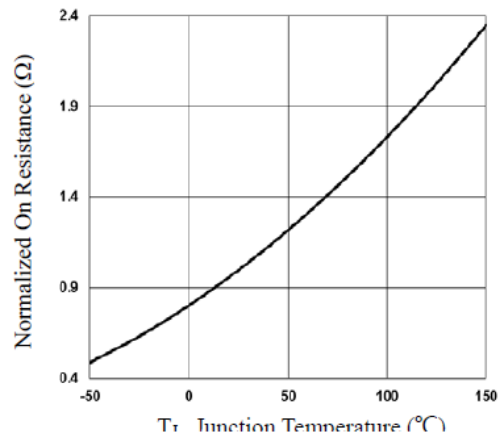
Note:

- The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
- Essentially independent of operating temperature.

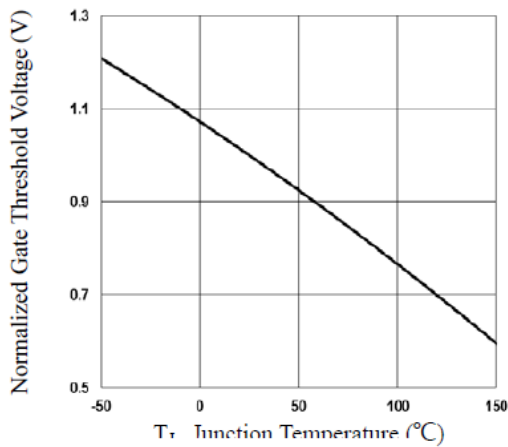
## Typical Performance Characteristics



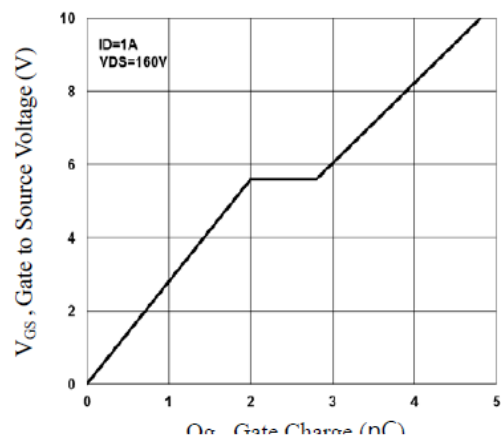
**Fig.1 Continuous Drain Current vs.  $T_c$**



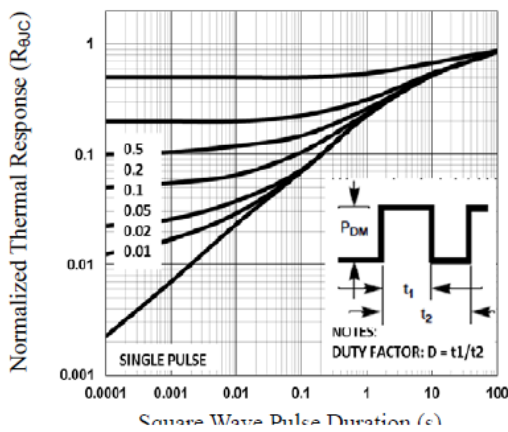
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$**



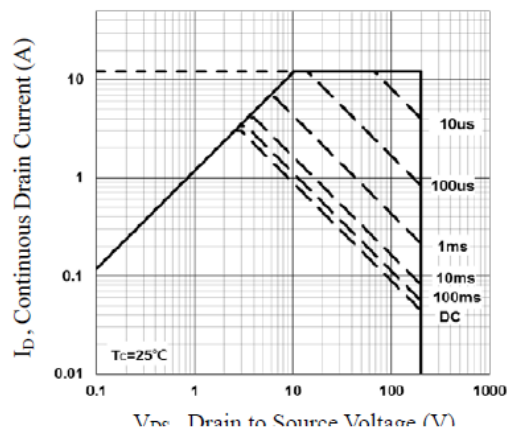
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



**Fig.4 Gate Charge Waveform**

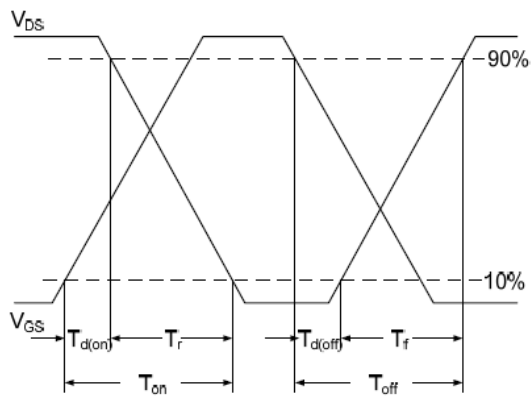


**Fig.5 Normalized Transient Impedance**

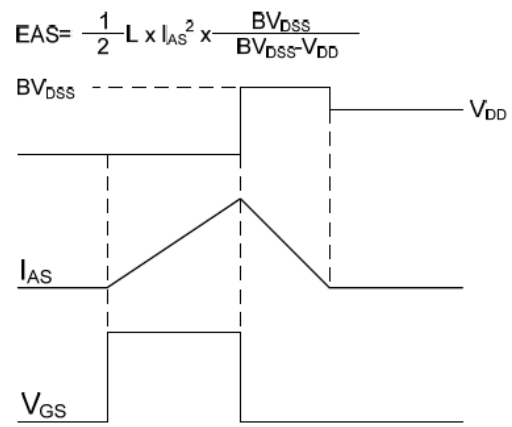


**Fig.6 Maximum Safe Operation Area**

## Typical Performance Characteristics (Continue)



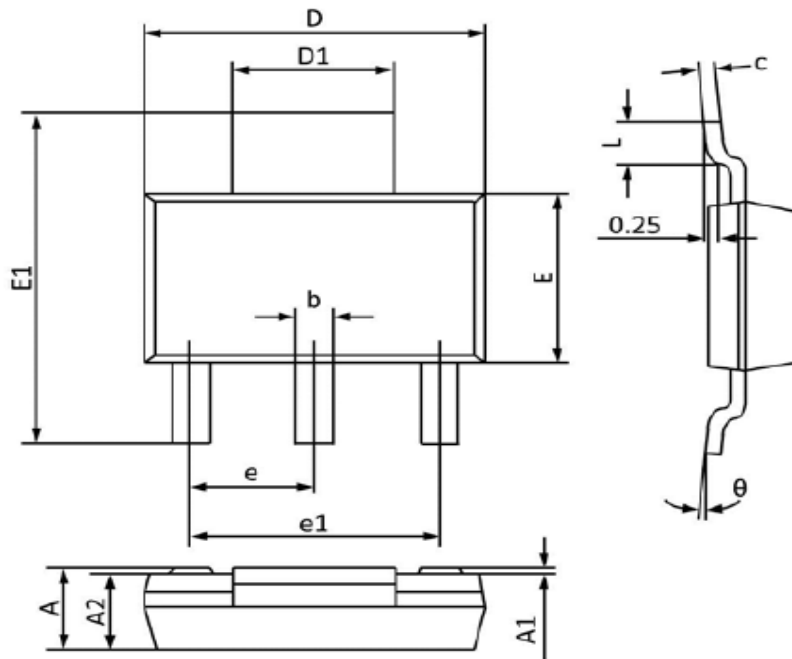
**Fig.7 Switching Time Waveform**



**Fig.8 EAS Waveform**

## Package Dimension

### SOT-223







### Dimensions



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	1.520	1.800	0.060	0.071
A1	0.000	0.100	0.000	0.004
A2	1.500	1.700	0.059	0.067
b	0.660	0.820	0.026	0.032
c	0.250	0.350	0.010	0.014
D	6.200	6.400	0.244	0.252
D1	2.900	3.100	0.114	0.122
E	3.300	3.700	0.130	0.146
E1	6.830	7.070	0.269	0.278
e	2.300 (BSC)		0.091 (BSC)	
e1	4.500	4.700	0.177	0.185
L	0.900	1.150	0.035	0.045
θ	0°	10°	0°	10°

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